



Materials Declaration

Package	MQFP
Body Size	28 X 28
LeadCount	208
Option	Pb-Free



Molding Compound			
Item	% of Compound	Weight (g)	PPM
Epoxy resin	10	3.46 E-01	63126
SiO2 Filler	84	2.90 E+00	530260
Phenol Resin	5.5	1.90 E-01	34719
Carbon Black	0.5	1.73 E-02	3156

Molding Compound		
Item	PPM	Method
Pb	4.40	EPA method #3052 (ICPAES)
Cd	<2.0	BS EN 1122:2001B (ICPaes)
Hg	<2.0	Mercury Analyser
Cr+6	<2.0	EPA method #3060A(UV)

Leadframe			
Item	% of Leadframe	Weight (g)	PPM
Cu	96.2	1.09 E+00	199102
Ni	3	3.40 E-02	6209
Si	0.65	7.37 E-03	1345
Mg	0.15	1.70 E-03	310

Die Attach Paste		
Item	PPM	Method
Pb	<5.0	ICP-AES
Cd	<5.0	ICP-AES
Hg	<5.0	ICP-AES
Cr+6	2.0	EPA method 7196A & EPA 3060A

Internal Leadframe Plating			
	% of Plating	Weight (g)	PPM
Ag	100	3.60 E-02	6572

External Leadframe Plating			
Item	% of Plating	Weight (g)	PPM
Sn	100	3.22 E-02	5877

Bond Wires			
	% of Wire	Weight (g)	PPM
Au	99.99	8.04 E-03	1468

Chip			
	% of Chip	Weight (g)	PPM
Si	100	7.53 E-01	137494

Die Attach			
Item	% of Die Attach	Weight (g)	PPM
Resin	23	1.31 E-02	2383
Ag Filler	77	4.37 E-02	7977

Package Totals		
	Weight (g)	PPM
	5.48 E+00	1000000

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.



ADI Proprietary



Materials Declaration

Package	MQFP
Body Size	28 X 28
LeadCount	208
Option	Sn/Pb



Molding Compound			
Item	% of Compound	Weight (g)	PPM
Epoxy resin	10	3.46 E-01	63126
SiO2 Filler	84	2.90 E+00	530260
Phenol Resin	5.5	1.90 E-01	34719
Carbon Black	0.5	1.73 E-02	3156

Molding Compound		
Item	PPM	Method
Pb	4.40	EPA method #3052 (ICPAES)
Cd	<2.0	BS EN 1122:2001B (ICPaes)
Hg	<2.0	Mercury Analyser
Cr+6	<2.0	EPA method #3060A(UV)

Leadframe			
Item	% of Leadframe	Weight (g)	PPM
Cu	96.2	1.09 E+00	199102
Ni	3	3.40 E-02	6209
Si	0.65	7.37 E-03	1345
Mg	0.15	1.70 E-03	310

Die Attach Paste		
Item	PPM	Method
Pb	<5.0	ICP-AES
Cd	<5.0	ICP-AES
Hg	<5.0	ICP-AES
Cr+6	2.0	EPA method 7196A & EPA 3060A

Internal Leadframe Plating			
Item	% of Plating	Weight (g)	PPM
Ag	100	3.60 E-02	6572

External Leadframe Plating			
Item	% of Plating	Weight (g)	PPM
Sn	85	2.74 E-02	4995
Pb	15	4.83 E-03	881

Bond Wires			
Item	% of Wire	Weight (g)	PPM
Au	99.99	8.04 E-03	1468

Chip			
Item	% of Chip	Weight (g)	PPM
Si	100	7.53 E-01	137494

Die Attach			
Item	% of Die Attach	Weight (g)	PPM
Resin	23	1.31 E-02	2383
Ag Filler	77	4.37 E-02	7977

Package Totals	
Weight (g)	PPM
5.48 E+00	1000000

Note: The information provided in this declaration are true to the best of ADI's knowledge. ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.



ADI Proprietary